



Material Content Data Sheet



Sales Product Name		SPD02N80C3		Issued		20. July 2018		
MA#		MA000453240						
Package		PG-TO252-3-341		Weight*		382.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.280	0.60	0.60	5966	5966
leadframe	non noble metal	iron	7439-89-6	0.248	0.06		650	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		195	
	non noble metal	copper	7440-50-8	248.124	64.96	65.04	649393	650238
wire	non noble metal	aluminium	7429-90-5	4.133	1.08	1.08	10817	10817
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.688	0.44		4418	
	plastics	brominated resin	-	1.809	0.47		4734	
	organic material	carbon black	1333-86-4	1.929	0.50		5050	
	plastics	epoxy resin	-	16.279	4.26		42607	
	inorganic material	silicondioxide	60676-86-0	98.882	25.88	31.55	258797	315606
leadfinish	non noble metal	tin	7440-31-5	3.787	0.99	0.99	9911	9911
plating	non noble metal	nickel	7440-02-0	0.515	0.13	0.13	1348	1348
solder	noble metal	silver	7440-22-4	0.058	0.02		153	
	non noble metal	tin	7440-31-5	0.047	0.01		122	
	non noble metal	lead	7439-92-1	2.231	0.58	0.61	5839	6114
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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